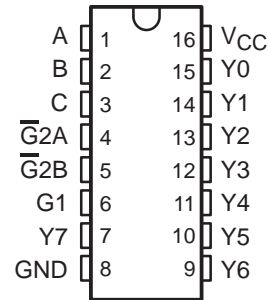


# SN54HC138, SN74HC138 3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS

SCLS107E – DECEMBER 1982 – REVISED SEPTEMBER 2003

- Targeted Specifically for High-Speed Memory Decoders and Data-Transmission Systems
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80- $\mu$ A Max  $I_{CC}$
- Typical  $t_{pd} = 15$  ns
- $\pm 4$ -mA Output Drive at 5 V
- Low Input Current of 1  $\mu$ A Max
- Incorporate Three Enable Inputs to Simplify Cascading and/or Data Reception

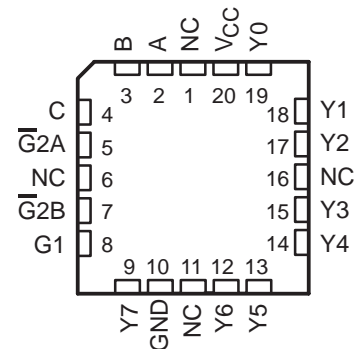
SN54HC138 . . . J OR W PACKAGE  
SN74HC138 . . . D, DB, N, NS, OR PW PACKAGE  
(TOP VIEW)



## description/ordering information

The 'HC138 devices are designed to be used in high-performance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of these decoders and the enable time of the memory are usually less than the typical access time of the memory. This means that the effective system delay introduced by the decoders is negligible.

SN54HC138 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 25	SN74HC138N	SN74HC138N
		Tube of 40	SN74HC138D	HC138
	SOIC – D	Reel of 2500	SN74HC138DR	
		Reel of 250	SN74HC138DT	
	SOP – NS	Reel of 2000	SN74HC138NSR	HC138
	SSOP – DB	Reel of 2000	SN74HC138DBR	HC138
	TSSOP – PW	Tube of 90	SN74HC138PW	HC138
Reel of 2000		SN74HC138PWR		
Reel of 250		SN74HC138PWT		
-55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC138J	SNJ54HC138J
	CFP – W	Tube of 150	SNJ54HC138W	SNJ54HC138W
	LCCC – FK	Tube of 55	SNJ54HC138FK	SNJ54HC138FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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 **TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN54HC138, SN74HC138

## 3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS

SCLS107E – DECEMBER 1982 – REVISED SEPTEMBER 2003

### description/ordering information (continued)

The conditions at the binary-select inputs at the three enable inputs select one of eight output lines. Two active-low and one active-high enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented without external inverters, and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications.

FUNCTION TABLE

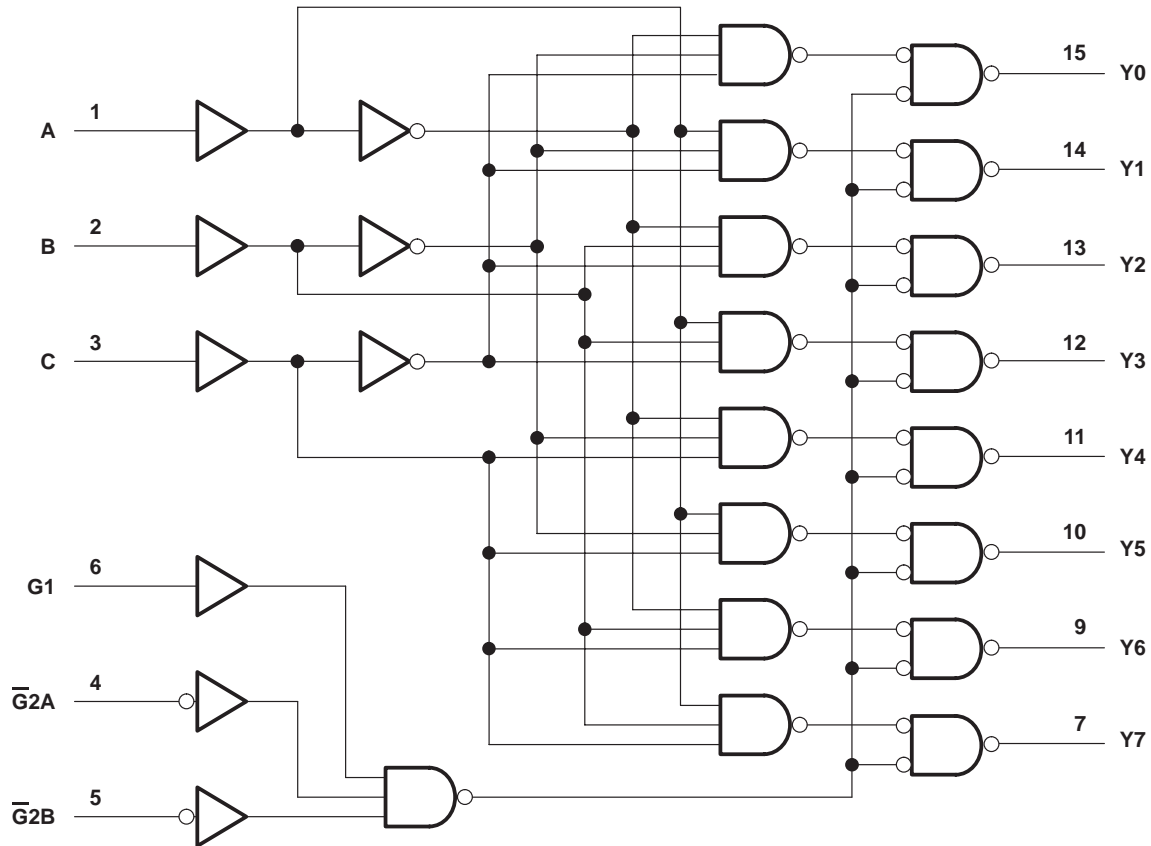
INPUTS						OUTPUTS							
ENABLE			SELECT										
G1	$\overline{G2A}$	$\overline{G2B}$	C	B	A	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
X	H	X	X	X	X	H	H	H	H	H	H	H	H
X	X	H	X	X	X	H	H	H	H	H	H	H	H
L	X	X	X	X	X	H	H	H	H	H	H	H	H
H	L	L	L	L	L	L	H	H	H	H	H	H	H
H	L	L	L	L	H	H	L	H	H	H	H	H	H
H	L	L	L	H	L	H	H	L	H	H	H	H	H
H	L	L	L	H	H	H	H	H	L	H	H	H	H
H	L	L	H	L	L	H	H	H	H	L	H	H	H
H	L	L	H	H	L	H	H	H	H	H	L	H	H
H	L	L	H	H	H	H	H	H	H	H	H	H	L



# SN54HC138, SN74HC138 3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS

SCLS107E – DECEMBER 1982 – REVISED SEPTEMBER 2003

## logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1) .....	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 25$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 50$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	
D package .....	73°C/W
DB package .....	82°C/W
N package .....	67°C/W
NS package .....	64°C/W
PW package .....	108°C/W
Storage temperature range, $T_{Stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN54HC138, SN74HC138

## 3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS

SCLS107E – DECEMBER 1982 – REVISED SEPTEMBER 2003

### recommended operating conditions (see Note 3)

		SN54HC138			SN74HC138			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	2	5	6	2	5	6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2\text{ V}$		1.5	1.5		V	
		$V_{CC} = 4.5\text{ V}$		3.15	3.15			
		$V_{CC} = 6\text{ V}$		4.2	4.2			
$V_{IL}$	Low-level input voltage	$V_{CC} = 2\text{ V}$			0.5	0.5	V	
		$V_{CC} = 4.5\text{ V}$			1.35	1.35		
		$V_{CC} = 6\text{ V}$			1.8	1.8		
$V_I$	Input voltage	0		$V_{CC}$	0	$V_{CC}$	V	
$V_O$	Output voltage	0		$V_{CC}$	0	$V_{CC}$	V	
$\Delta t/\Delta v$	Input transition rise/fall time	$V_{CC} = 2\text{ V}$			1000	1000	ns	
		$V_{CC} = 4.5\text{ V}$			500	500		
		$V_{CC} = 6\text{ V}$			400	400		
$T_A$	Operating free-air temperature	-55		125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC138		SN74HC138		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$V_{OH}$	$V_I = V_{IH}$ or $V_{IL}$	$I_{OH} = -20\ \mu\text{A}$	2 V	1.9	1.998		1.9	1.9	V		
			4.5 V	4.4	4.499		4.4	4.4			
			6 V	5.9	5.999		5.9	5.9			
		$I_{OH} = -4\text{ mA}$	4.5 V	3.98	4.3		3.7	3.84			
		$I_{OH} = -5.2\text{ mA}$	6 V	5.48	5.8		5.2	5.34			
$V_{OL}$	$V_I = V_{IH}$ or $V_{IL}$	$I_{OL} = 20\ \mu\text{A}$	2 V		0.002	0.1		0.1	0.1	V	
			4.5 V		0.001	0.1		0.1	0.1		
			6 V		0.001	0.1		0.1	0.1		
		$I_{OL} = 4\text{ mA}$	4.5 V		0.17	0.26		0.4	0.33		
		$I_{OL} = 5.2\text{ mA}$	6 V		0.15	0.26		0.4	0.33		
$I_I$	$V_I = V_{CC}$ or 0		6 V		$\pm 0.1$	$\pm 100$		$\pm 1000$	$\pm 1000$	nA	
$I_{CC}$	$V_I = V_{CC}$ or 0, $I_O = 0$		6 V			8		160	80	$\mu\text{A}$	
$C_i$			2 V to 6 V		3	10		10	10	pF	



# SN54HC138, SN74HC138 3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS

SCLS107E – DECEMBER 1982 – REVISED SEPTEMBER 2003

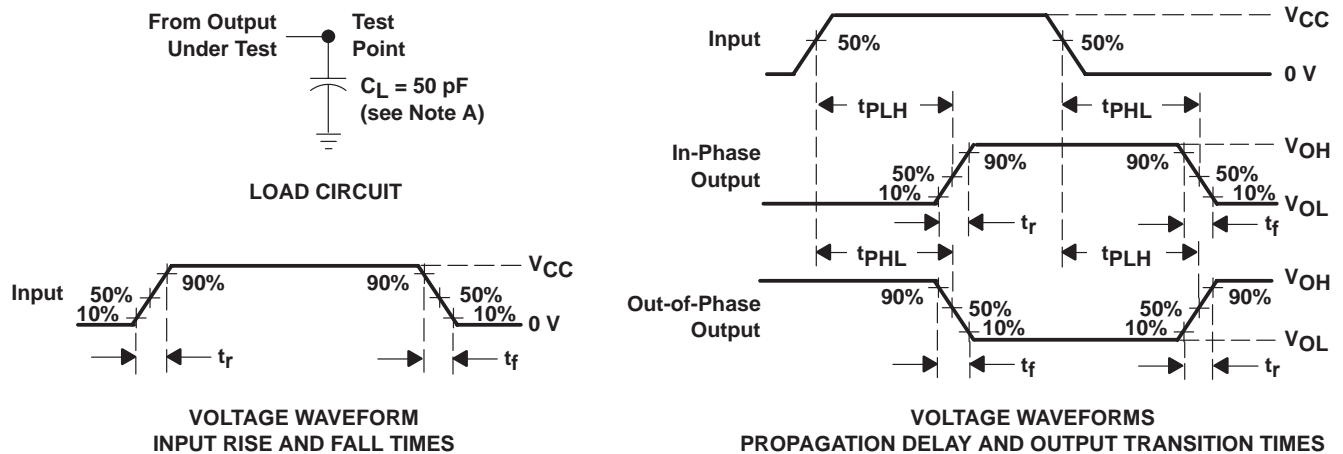
switching characteristics over recommended operating free-air temperature range,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC138		SN74HC138		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A, B, or C	Any Y	2 V	67	180	270	225	ns			
			4.5 V	18	36	54	45				
			6 V	15	31	46	38				
	Enable	Any Y	2 V	66	155	235	195				
			4.5 V	18	31	47	39				
			6 V	15	26	40	33				
$t_t$		Any	2 V	38	75	110	95	ns			
			4.5 V	8	15	22	19				
			6 V	6	13	19	16				

operating characteristics,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance	No load	85	pF

## PARAMETER MEASUREMENT INFORMATION



- NOTES:
- $C_L$  includes probe and test-fixture capacitance.
  - Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r = 6$  ns,  $t_f = 6$  ns.
  - The outputs are measured one at a time with one input transition per measurement.
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-8406201VEA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
5962-8406201VFA	ACTIVE	CFP	W	16	1	None	Call TI	Level-NC-NC-NC
84062012A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
8406201EA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
8406201FA	ACTIVE	CFP	W	16	1	None	Call TI	Level-NC-NC-NC
JM38510/65802B2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
JM38510/65802BEA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
JM38510/65802BFA	ACTIVE	CFP	W	16	1	None	Call TI	Level-NC-NC-NC
SN54HC138J	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SN74HC138D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC138DBR	ACTIVE	SSOP	DB	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC138DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC138DT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC138N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC138N3	OBSOLETE	PDIP	N	16		None	Call TI	Call TI
SN74HC138NSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC138PW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC138PWLE	OBSOLETE	TSSOP	PW	16		None	Call TI	Call TI
SN74HC138PWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC138PWT	ACTIVE	TSSOP	PW	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54HC138FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54HC138J	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SNJ54HC138W	ACTIVE	CFP	W	16	1	None	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**None:** Not yet available Lead (Pb-Free).

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-012 variation AC.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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